

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Yang, et al.

Serial No.: 10/627,336

Confirmation No.: 2292


Filed: July 24, 2003

For: Electrochemical Processing Cell

Group Art Unit: 1742

Examiner: Zheng, Lois L.

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING OR TRANSMISSION	
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, or electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner Zheng, on the date shown below.	
Date 11/7/06	 Steven H VerSteeg

Dear Sir:

DECLARATION UNDER 37 C.F.R. § 1.132

I, an undersigned inventor, Michael X. Yang, hereby declare as follows:

1. I am one of the co-inventors of the subject matter claimed in United States Patent Application Publication No. 2004/0016647 A1 and the present application;
2. Dmitry Lubomirsky, Yezdi N. Dordi, Saravjeet Singh, Sheshraj L. Tulshibagwale, Nicolay Y. Kovarsky, and myself are the inventors of the subject matter claimed in the present invention;
3. Any subject matter claimed in the present application that was disclosed, but not claimed in United States Patent Application Publication No. 2004/0016647 A1, was

invented by Dmitry Lubomirsky, Yezdi N. Dordi, Saravjeet Singh, Sheshraj L. Tulshibagwale, Nicolay Y. Kovarsky, and myself;


4. The subject matter claimed in United States Patent Application Publication No. 2004/0016647 A1 was invented by Nicolay Y. Kovarsky and myself. The subject matter claimed is directed to a method for plating copper.

5. The subject matter claimed in the present application is directed to an electrochemical plating cell.

6. All statements made herein of my own knowledge are true and that these statements made on information and belief are believed to be true and further that these statements were made with knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of this application or any patent resulting therefrom.

Oct 9, 2006

Date



Michael X. Yang